

ABSTRACT

A substrate, such as a semiconductor wafer, is cut without using a dicer or an adhesive sheet.

A semiconductor wafer 1 formed with a number of elements 2 is drawn and held by an x-y table 4, and ultrashort pulse laser 7 having a pulse width of not more than 1 picosecond is irradiated along scribed lines between the elements 2 to cut the same.